



## Product End-of-Life Disassembly Instructions

**Product Category: External Options**

**Marketing Name / Model**  
**[List multiple models if applicable.]**

OMEN by HP 17 Laptop PC

OMEN by HP Laptop

OMEN by HP Laptop 17

**Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).**

**NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact [HP's Sustainability Contact](#).**

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries, excluding Li-Ion batteries.	All types including standard alkaline, coin or button style batteries	0
Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)	Battery(ies) are attached to the product by ( <i>check all that apply with an "x" inside the "[ ]"</i> ): [4] screws [0] snaps [0] adhesive [ ] other. Explain _____ NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring		

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HPI instructions for this template are available at [EL-MF877-01](#)

Item Description	Notes	Quantity of items included in product
greater than 2.5 cm in diameter or height		
External electrical cables and cords	DC Cable for External Power Supply	2
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove lower
2. Remove battery
3. Remove HDD
4. Remove bracket and DC-in cable
5. Remove thermal module
6. Remove IO/B
7. Remove wlan card, SSD bracket, SSD module
8. Remove MB
9. Remove Power/B, Sensor/B
10. Remove speaker, TP button
11. Remove hinge up
12. Remove Bezel
13. Remove hinge
14. Remove Panel
15. Remove Panel bracket
16. Remove antenna cable, camera module

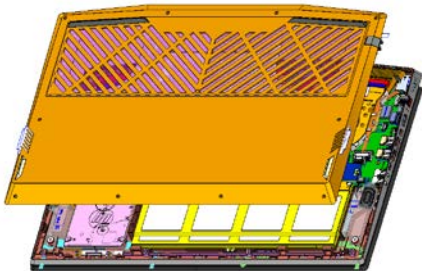
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HPI instructions for this template are available at [EL-MF877-01](#)

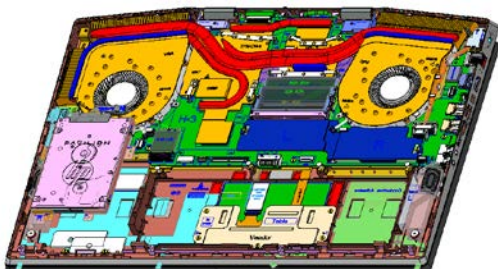
**3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).**



step 1, remove lower



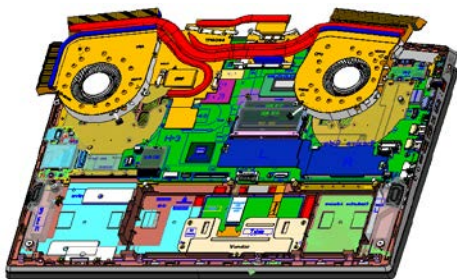
step 2, remove battery



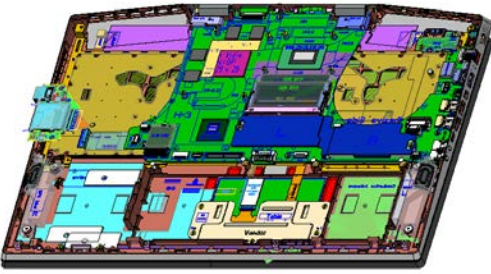
step 3, remove HDD



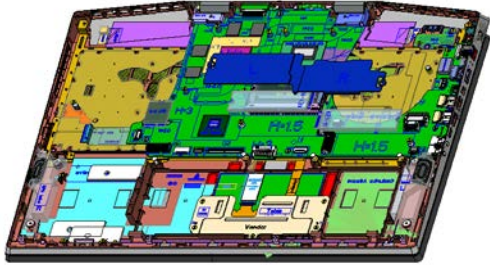
step 4, remove bracket and DC-in cable



step 5, remove thermal module



step 6, remove IO/B



step 7, remove wlan card, SSD bracket, SSD module



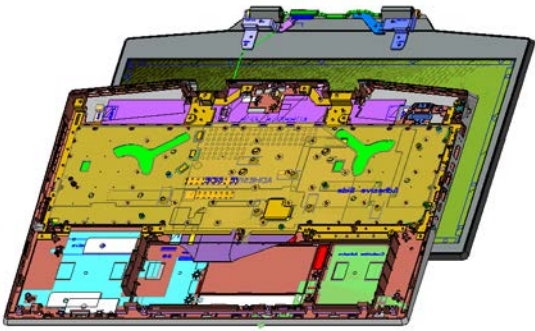
step 8, remove MB



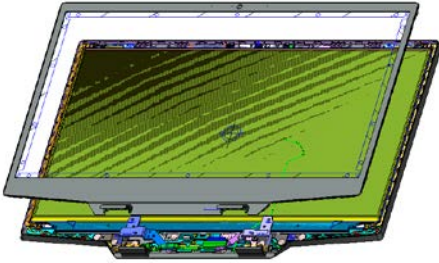
step 9, remove Power/B, Sensor/B



step 10, remove speaker, TP button



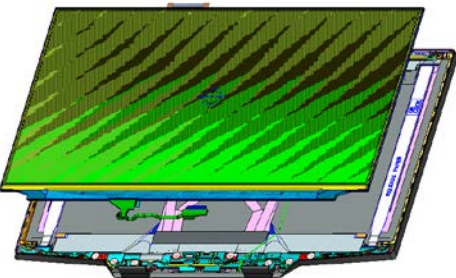
step 11, remove hinge up



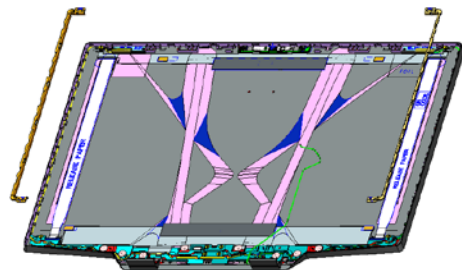
step 12, remove Bezel



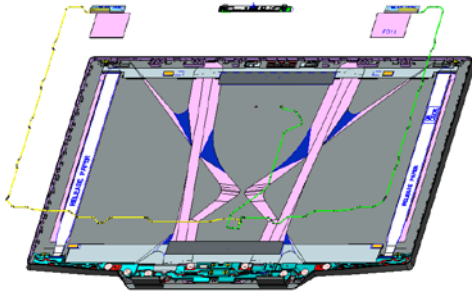
step 13, remove hinge



step 14, remove panel



step 15, remove panel bracket



step 16, remove antenna, camera module